

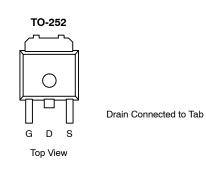
### APM2023N-VB Datasheet

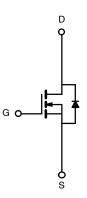
## N-Channel 20-V (D-S)175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>		
20	0.0045 @ V <sub>GS</sub> = 4.5 V	100		
20	0.006 @ V <sub>GS</sub> = 2.5 V	90		

#### **FEATURES**

- TrenchFET® Power MOSFET
- 175°C Maximum Junction Temperature
- 100% R<sub>g</sub> Tested





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C UNLESS OTHERWISE NOTED)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	N N	
Gate-Source Voltage		V <sub>GS</sub>	±15	- V	
	$T_C = 25^{\circ}C$		100		
Continuous Drain Current <sup>a</sup>	$T_{C} = 100^{\circ}C$	, I <sub>D</sub>	80		
Pulsed Drain Current		I <sub>DM</sub>	200	A	
Continuous Source Current (Diode Conduction) <sup>a</sup>		Is	65		
M · D D · · · ·	$T_C = 25^{\circ}C$		71		
Maximum Power Dissipation	$T_A = 25^{\circ}C$	P <sub>D</sub>	8.3 <sup>b, c</sup>	- w	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
	$t \le 10$ sec.		15	18	°C/W	
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	40	50		
Maximum Junction-to-Case		R <sub>thJC</sub>	1.75	2.1		

Notes

a. Package Limited

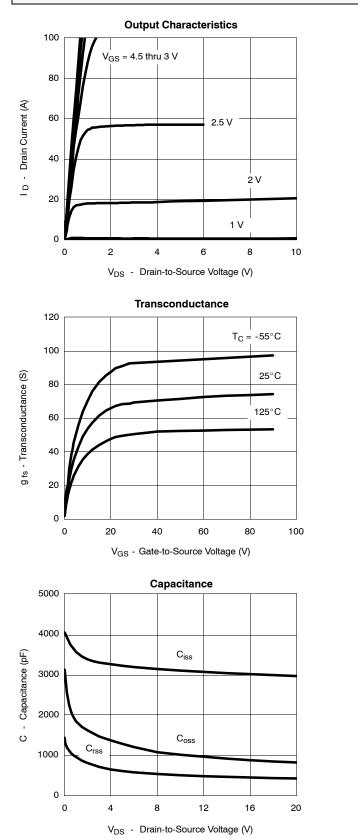
b. Surface Mounted on 1" x 1" FR4 Board

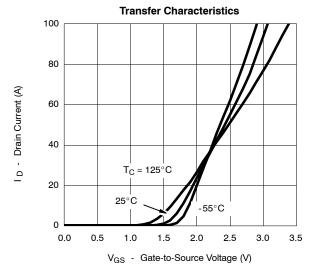
 $\text{c.} \quad t \, \leq \, 10 \, \, \text{sec}$ 

Parameter	Symbol	Test Condition	Min	Typ <sup>a</sup>	Max	Unit	
Static				1			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu$ A	20			v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\;\mu A$	0.5		1.5	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ±12 V			±100	nA	
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 $^{\circ}\text{C}$			50	μΑ	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS}$ = 5 V, $V_{GS}$ = 4.5 V	100			А	
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.0045		Ω	
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	$V_{GS}$ = 4.5 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0055			
		$V_{GS}$ = 2.5 V, I <sub>D</sub> = 20 A		0.006		1	
Forward Transconductanceb	9fs	$V_{DS} = 5 \text{ V}, \text{ I}_{D} = 40 \text{ A}$	20			S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			3660			
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 20 V, f = 1 MHz		730		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			375			
Total Gate Charge <sup>c</sup>	Qg			26	35	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 10 V, $V_{GS}$ = 4.5 V, $I_{D}$ = 40 A		5			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			7		1	
Gate Resistance	Rg		1		3.7	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	35		
Rise Time <sup>c</sup>	tr	$V_{DD}$ = 10 V, $R_L$ = 0.25 $\Omega$		120	190	- ns	
Turn-Off Delay Timec	t <sub>d(off)</sub>	$I_D \cong$ 40 Å, $V_{GEN}$ = 4.5 V, $R_G$ = 2.5 $\Omega$		45	70		
Fall Time <sup>c</sup>	t <sub>f</sub>			20	35		
Source-Drain Diode Ratings a	nd Characteristi	c (T <sub>C</sub> = 25°C)					
Pulsed Current	I <sub>SM</sub>				100	А	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 100 A, V <sub>GS</sub> = 0 V		1.2	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 40 A, di/dt = 100 A/µs		35	70	ns	



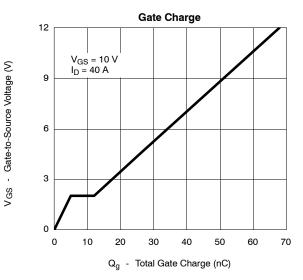
#### **TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**



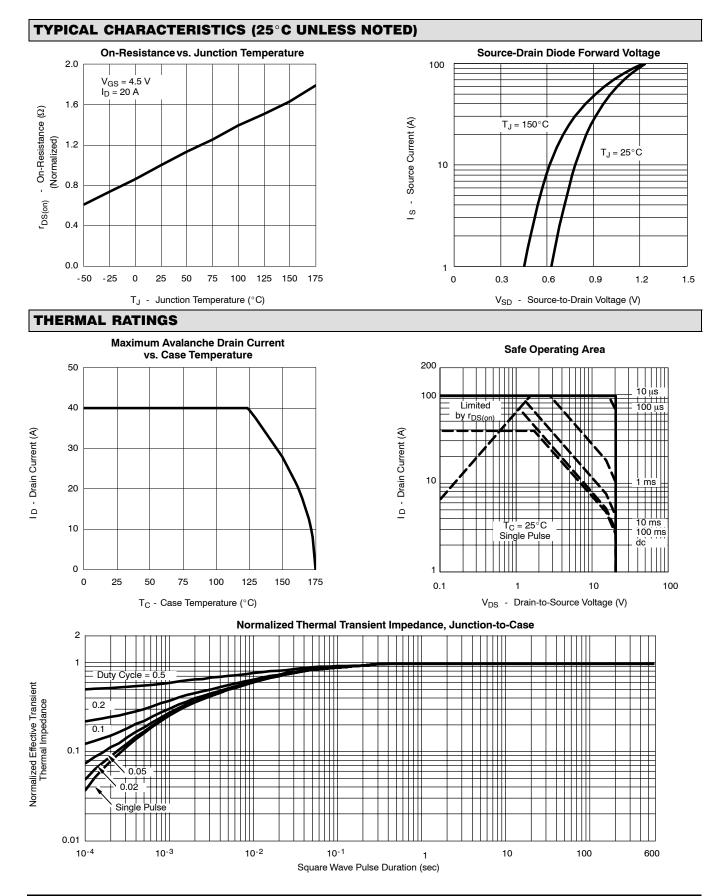


On-Resistance vs. Drain Current 0.012 0.009 V<sub>GS</sub> = 4.5 V V<sub>GS</sub> = 4.5 V 0.006 0.000 0



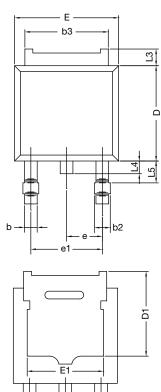


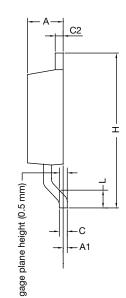






## **TO-252AA CASE OUTLINE**





	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	BSC	0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12- DWG: 534	0247-Rev. M, 7	24-Dec-12			

Note

• Dimension L3 is for reference only.



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